

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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2 PRODUCT MAY BE PROTECTED BY ONE OR MORE OF THE FOLLOWING US PATENTS: 5736910 5939955 6425781 6428361 6554638 6840817 7123117 7429195 7717749 7808751 6217391 6149050 7924130 THIS DRAWING AND THE SUBJECT MATTER SHOWN THEREON ARE CONFIDENTIAL AND THE PROPERTY REVISIONS OF BEL/STEWART/TRP CONNECTOR AND SHALL NOT BE REPRODUCED, COPIED, OR USED IN ANY MANNER WITHOUT THE WRITTEN CONSENT OF TRP CONNECTOR. EC-1411035, COMPANY LOGO CHANGE TR TY 11FEB2015 - HOUSING: THERMOPLASTIC, BLACK, FLAMMABILITY RATING UL 94V-0. SHIELD: BRASS, PREPLATED WITH 0.76um MIN SEMI-BRIGHT NICKEL, POST DIPPED WITH 2.54um MIN SAC SOLDER ON SOLDER TAILS.
 CONTACTS: PHOSPHOR BRONZE, PLATED WITH 1.27um MIN OVERALL NICKEL UNDERPLATE, SELECTIVE 1.27um MIN GOLD AT MATING INTERFACE AND 2.54um MIN MATTE TIN ON SOLDER TAILS - LED: DIFFUSED EPOXY LENS, CARBON STEEL LEAD FRAME LEADS, PREPLATED WITH 2.03um MIN SILVER OVER 1.02um MIN NICKEL OVER 1.02um MIN COPPER UNDERPLATE, POST PLATED WITH 2.54um MIN MATTE TIN AND/OR 2.54um MIN SAC SOLDER DIP OR PURE TIN SOLDER DIP. /2\ MAGNETICS -APPLICATION: 10/100/1000 BASE-T -IMPEDANCE: 100 OHMS -TURNS RATIO (CHIP:CABLE): 1:1 ALL FOUR PAIRS -OPEN CIRCUIT INDUCTANCE (OCL): 350uH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0 °C TO 70 °C, ALL FOUR PAIRS -ALL FOUR PAIRS BI-DIRECTIONAL -PERFORMANCE @ 25 ° C: INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 40MHz 12-20LOG(f/80)dB MIN FROM 40.1MHz TO 100MHz CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz 33-20LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz -ISOLATION VOLTAGE: COMPLIES WITH IEEE802.3 2002, PARA 40.6.1.1, ITEM b. S8G17 GIGABIT CIRCUIT AA A PART NUMBER, DATE CODE AND COUNTRY OF ORIGIN ARE LOCATED IN THE APPROXIMATE AREA SHOWN.DATE CODE "YY" IS THE YEAR, "WW" IS THE WEEK, "D" IS THE DAY OF WEEK, WITH **Top and Bottom Ports** 4 TRP AND AGENCY APPROVAL LOGO ARE LOCATED IN THE APPROXIMATE AREA SHOWN. MX0-Pin Designations 5 RJ45 CAVITIES CONFORM TO FCC RULES AND REGULATION PART 68 SUBPART F. (Repeat for each vertical pair of ports.) (2) MX0+ TD0+ RJ-1 LEDS ARE DRIVEN WITH CONSTANT CURRENT AT APPROX. 20mA. 010 100 09 _ DOMINANT WAVELENGTH (AD) Stood 100 09 Top Ports 100 09 (3) MX1-TD0- RJ-2 GREEN, 568nm TYP AT IF=20mA 1CT:1CT PCB Pins YELLOW, 588nm TYP AT IF=20mA CMC2 T2 (Top View, -(4) MX1+ TD1+ RJ-3 FORWARD VOLTAGE(VF) Comp. Side) GREEN, 2.2V TYP AT IF=20mA YELLOW, 2.1V TYP AT IF=20mA -(5) MX2-TD2+ RJ-4 1CT:1CT / INDICATED MAGNETIC CONNECTIONS ARE SYMMETRICAL AND SUPPORT AUTO-MDI/MDIX. CMC3 (6) MX2+ TD2- RJ-5 8 OPERATING TEMPERATURE: FROM 0 ° C TO 70 ° C TD1- RJ-6 -(7) MX3-1CT:1CT RJ Cable THE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS, PEAK TEMPERATURE IS 265° C MAX, 10 SECONDS MAX.IT IS RECOMMENDED THAT THE CONNECTOR SHIELD AND BODY BE MASKED CMC4 T4 Contacts -(8) MX3+ TD3+ RJ-7 TO PROTECT IT FROM DIRECT EXPOSURE TO THE SOLDER WAVE TO AVOID DAMAGE TO THE CONNECTOR AND LEDS. -(9) vcc TD3- RJ-8 1CT:1CT C3 -(10) GND C1 SHIELD 1. C1 = 1000pF,2KV,10%,X7R GREEN /YELLOW GREEN/YELLOW GREEN/YELLOW GREEN/YELLOW 1840242-1 2. C2, C3 = 470pF, 10%, 50V REAR PCB GND TABS BOTTOM LED 2 (LEFT) BOTTOM LED 1 (RIGHT) TOP LED 2 (LEFT) TOP LED 1 (RIGHT) PART NUMBER

30JUL2007 THIS DRAWING IS A CONTROLLED DOCUMENT. dwn Dale Pan 30JUL2007 KEITH ZHU
APVD
TEDDY XIONG
MODEL NAME CONNECTOR DONGGUAN TOLERANCES UNLESS OTHERWISE SPECIFIED: 30JUL2007 mm ±0.25 ±0.25 ±0.25 2X2 S8G17 GIGABIT OFFSET W/ LED MAGJACK STACK NON-PoE PRODUCT SPEC **C**-1840242

CUSTOMER DRAWING

SCALE NTS SHEET 1 OF 4

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